



DESCRIPTION

$V_{DS}=30V$

$V_{GS}=\pm 20V$

$ID(A)=5.5A$

$R_{DS(ON)}=22m\Omega$ (Typ.) @ $V_{GS}=10V$

$R_{DS(ON)}=32m\Omega$ (Typ.) @ $V_{GS}=4.5V$

AM2304A is available in a SOT-23 package.

FEATURES

- Fast switch
- Available in a SOT-23 package.

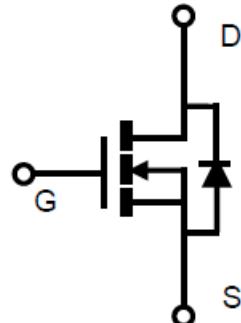
ORDERING INFORMATION

Package Type	Part Number	
SOT-23 SPQ: 3,000pcs/Reel	E3	AM2304AE3R
		AM2304AE3VR
Note	V: Halogen free Package R: Tape & Reel	
AiT provides all RoHS products		

APPLICATION

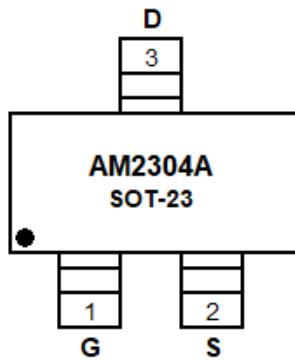
- Hand-Held Instruments
- Load Switch
- DC/DC Converter

N CHANNEL MOSFET





PIN DESCRIPTION



Top View

Pin #	Symbol	Function
1	G	Gate
2	S	Source
3	D	Drain



ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ\text{C}$, unless otherwise noted

V_{DSS} , Drain-Source Voltage	30V				
V_{GSS} , Gate-Source Voltage	$\pm 20\text{V}$				
I_D , Continuous Drain Current ^{NOTE1}	$T_A=25^\circ\text{C}$	5.5A			
	$T_A=70^\circ\text{C}$	4.4A			
I_{DM} , Pulsed Drain Current ^{NOTE2}	22A				
I_{AS} , Avalanche Current ^{NOTE2}	8A				
E_{AS} , Single Pulse Avalanche Energy $L=0.1\text{mH}$ ^{NOTE2}	3.2mJ				
P_D , Power Dissipation ^{NOTE1}	$T_A=25^\circ\text{C}$	1.3W			
	$T_A=70^\circ\text{C}$	0.84W			
T_J , Operation Junction Temperature	$-55^\circ\text{C} \sim 150^\circ\text{C}$				
T_{STG} , Storage Temperature Range	$-55^\circ\text{C} \sim 150^\circ\text{C}$				

Stress beyond above listed "Absolute Maximum Ratings" may lead permanent damage to the device. These are stress ratings only and operations of the device at these or any other conditions beyond those indicated in the operational sections of the specifications are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

THERMAL CHARACTERISTICS

Parameter		Symbol	Typ	Max	Units
Thermal Resistance Junction to Ambient ^{NOTE1}	$t \leq 10\text{s}$	$R_{\theta JA}$	-	95	$^\circ\text{C/W}$
Thermal Resistance Junction to Ambient ^{NOTE1, 3}	Steady-State		-	130	



ELECTRICAL CHARACTERISTICS

T_A = 25°C, unless otherwise noted

Parameter	Symbol	Conditions	Min	Typ.	Max	Units
Static Parameters						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _S =250μA	30	-	-	V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1	1.5	2	V
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V, T _J =25°C	-	-	1	μA
		V _{DS} =24V, V _{GS} =0V, T _J =75°C	-	-	10	
Drain-source On-Resistance ^{NOTE4}	R _{D(ON)}	V _{GS} =10V, I _D =5.5A	-	22	26	mΩ
		V _{GS} =4.5V, I _D =4.5A	-	32	42	
Forward Transconductance	G _f	V _{DS} =10V, I _D =3A	-	6.8	-	S
Diode Characteristics						
Diode Forward Voltage ^{NOTE4}	V _{SD}	I _S =1A, V _{GS} =0V	-	-	1	V
Diode Continuous Forward Current	I _S		-	-	2.8	A
Dynamic and Switching Parameters^{NOTE5}						
Total Gate Charge	Q _g	V _{DS} =15V, V _{GS} =10V, I _D =5A	-	7.6	10.6	nC
Total Gate Charge (4.5V)	Q _g		-	3.7	5.2	
Gate-Source Charge	Q _{gs}		-	1.5	2.1	
Gate-Drain Charge	Q _{gd}		-	1.6	2.2	
Input Capacitance	C _{iss}	V _{DS} =15V, V _{GS} =0V, f=1MHz	-	320	-	pF
Output Capacitance	C _{oss}		-	55	-	
Reverse Transfer Capacitance	C _{rss}		-	42	-	
Turn-On Time	t _{d(on)}	V _{DD} =15, V _{GEN} =10V R _G =6Ω, I _D =1A	-	2.65	5	ns
	t _r		-	8.5	16	
Turn-Off Time	t _{d(off)}		-	18.2	35	
	t _f		-	5	10	

NOTE1: Surface mounted on FR4 board using 1 in² pad size.

NOTE2: Pulsed width limited by maximum junction temperature, T_{J(MAX)}=150°C.

NOTE3: Using ≤ 10s junction-to-ambient thermal resistance is base on T_{J(MAX)}=150°C.

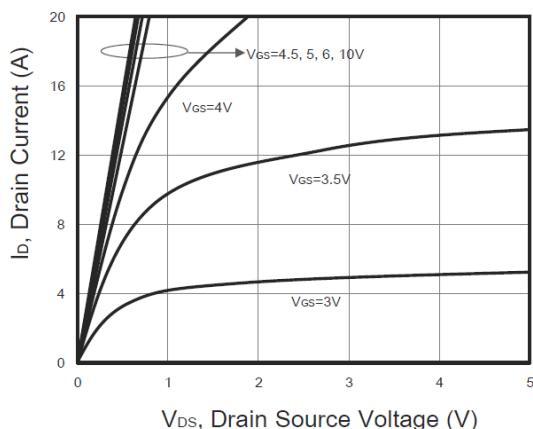
NOTE4: Pulse test width ≤300μs and duty cycle ≤ 2%.

NOTE5: Guaranteed by design, not subject to production testing.

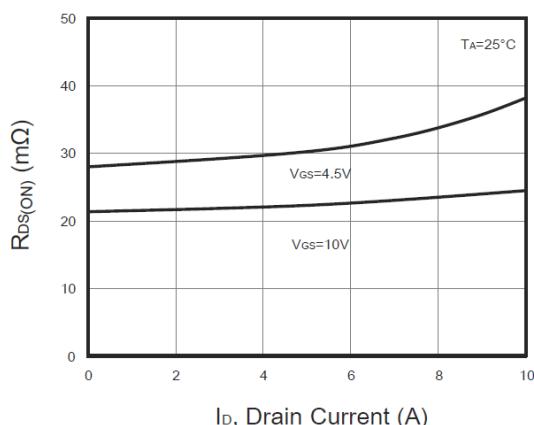


TYPICAL CHARACTERISTICS

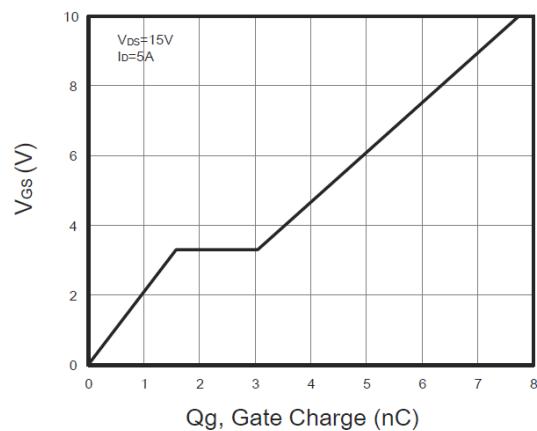
1. Output Characteristics



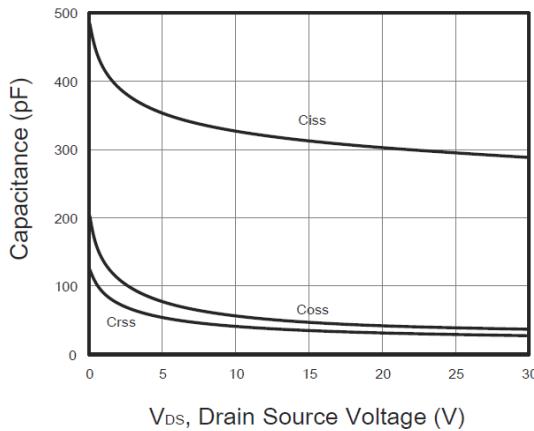
2. Drain-Source On Resistance



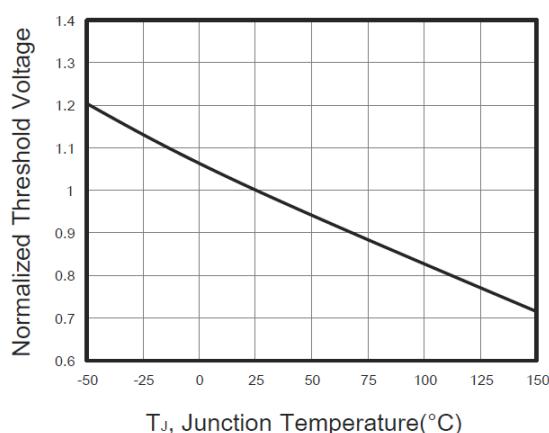
3. Gate Charge



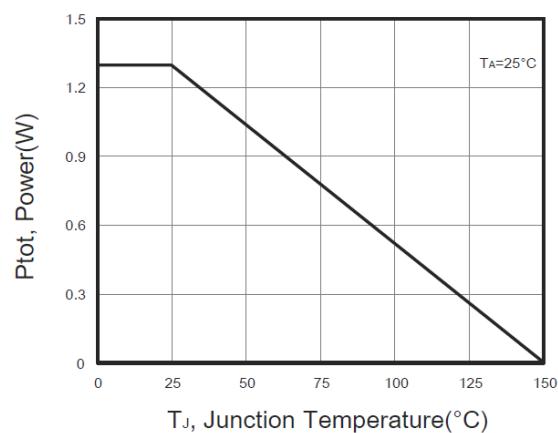
4. Capacitance



5. Gate Threshold Voltage

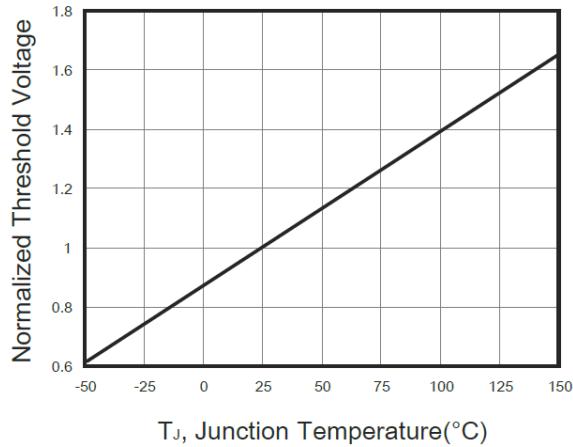


6. Power Dissipation

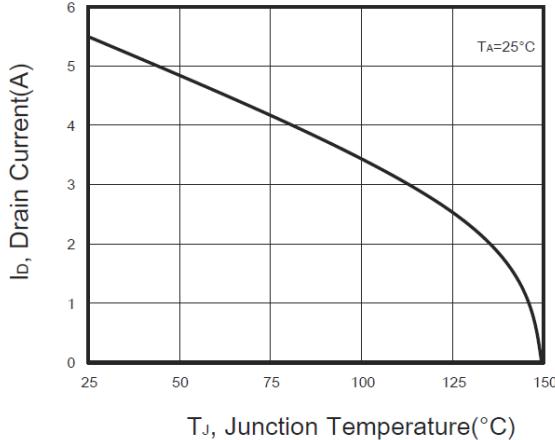




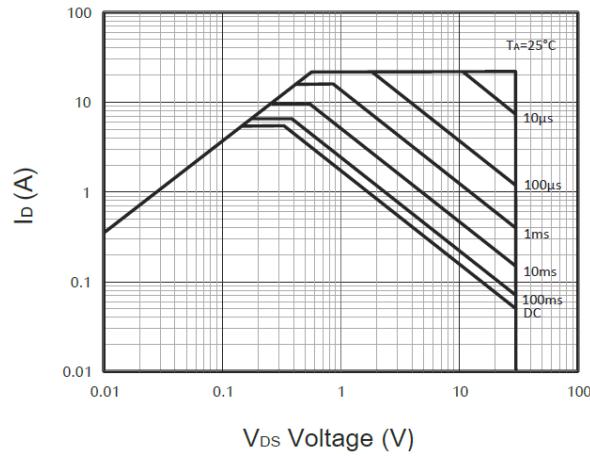
7. Gate Threshold Voltage



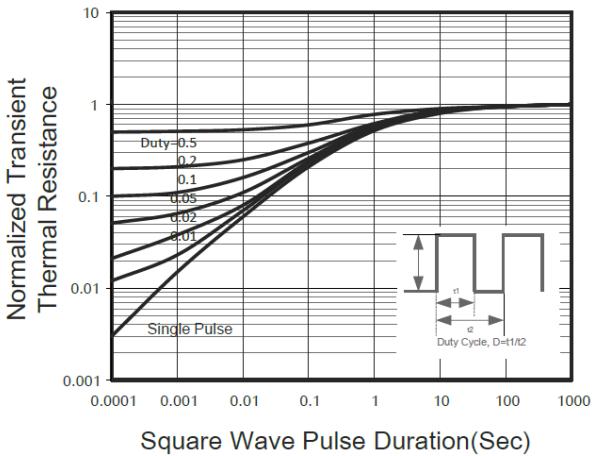
8. Drain Current vs. T_J



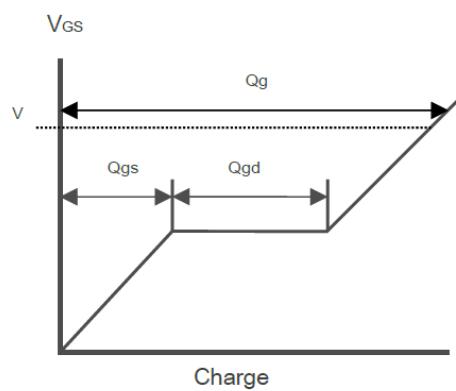
9. Maximum Safe Operation Area



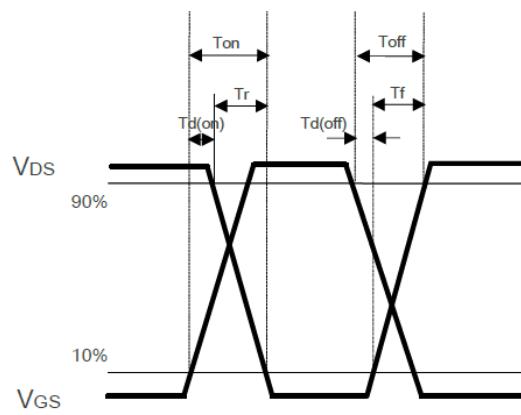
10. Thermal Transient Impedance



11. Gate Charge Waveform



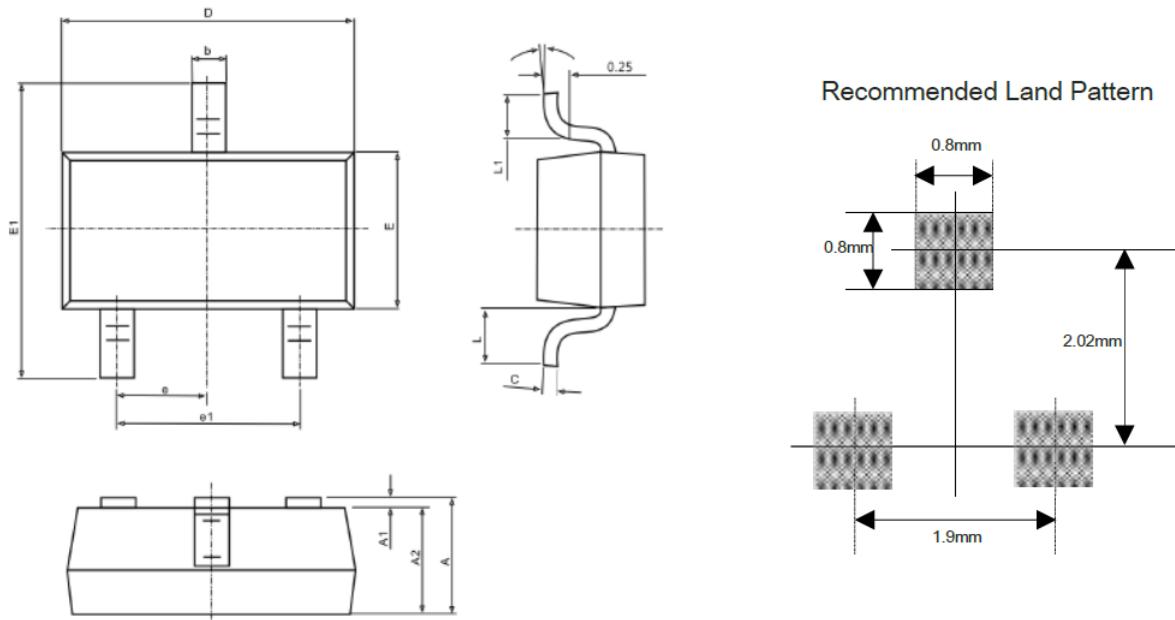
12. Switching Time Waveform





PACKAGE INFORMATION

Dimension in SOT-23 Package (Unit: mm)



Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°



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